有关敝公司产品的注意事项

请务必在使用敝公司产品之前阅读。

⚠ 注 意

产品目录中的记载内容

本产品目录中所记载的内容为2023年3月的内容。因产品改良等原因，可能会不经预告而变更其记载内容，或是停止供应本产品目录中所记载的产品。所以，请务必在使用前先确认最新的产品信息。

未按照本产品目录中所记载的内容或交货规格说明书使用敝公司产品的，即便其致使用设备发生损害、不良情况等时，敝公司也不承担任何责任，敬请知悉。

签署交货规格说明书

就本产品目录中所记载产品的产品规格等相关内容，敝公司备有交货规格说明书，详情请向敝公司咨询。在使用敝公司产品前请务必就交货规格说明书之内容确认并批准之。

实装前的事前评估

使用敝公司产品时，请务必事先安装到使用设备之后，在实际使用的环境下进行评估和确认。

用途的限定

1. 可以使用的设备

本产品目录中所记载的产品预设为使用于一般民用电子设备［音像设备、办公自动化设备、家电产品、办公设备、信息通讯设备（手机、电脑等）］以及面向本产品目录或是交货规格说明书中另行注明的设备或是敝公司另行承诺的设备的通用性，标准性用途。另外，面向下述设备的应用，敝公司也备有预设的产品系列，请参考本产品目录或是交货规格说明书的内容，使用相对应的产品。

用途	产品系列		品质等级(注释3)
	对象设备(注释1)	规格号（型号标记(注释2)）	
车载	汽车用电子设备（控制系 / 安全系）	A	1
	汽车用电子设备（车身系 / 情报系）	C	2
工业	通信基础设备·工业设备	B	2
医疗	医疗设备（国际（GHTF）第三类）	M	2
	医疗设备（国际（GHTF）第一类、第二类）	L	3
民用	一般电子设备	S	3
	移动设备专用(注释4)	E	4

注释1：基于敝公司所认知的该类设备对于电子元器件所需的一般要求规格，对于该产品系列进行的应用推荐。在讨论将各个产品系列使用在对象设备以外的设备上时，请务必事先向敝公司咨询。

注释2：在产品型号中左起第2位标注有上表中所记载的“规格号”。对于相关的详细内容，请参照有关各产品型号标示法的说明资料。

注释3：在各产品系列中，都设定了从上至下1至4的“品质等级”。另外，在未得到敝公司的事前书面承诺之前，请勿将敝公司的产品使用于相对于该产品的品质等级被设定为上位品质等级的设备。

注释4：本产品系列仅可应用于一般民用电子设备中的移动设备（智能手机、平板电脑、智能手表、掌上游戏机等）。由于其设计、规格和使用环境与面向“一般电子设备”的产品系列（规格号：S）不同，有关本产品系列的详细信息请参照交货规格说明书。另外，面向“一般电子设备”的产品系列（规格号：S）也可以应用于移动设备。

▶由于篇幅有限，本产品目录中只记载了有代表性的产品规格，若考虑使用敝公司产品时，请确认交货规格说明书中的详细规格。另外，有关各产品的详细信息(特性图、可靠性信息、使用时的注意事项等)，请参阅敝公司网站(http://www.ty-top.com/)。

2. 需要另行确认的设备

若考虑将本产品目录中所记载的产品使用于当产品发生故障、品质不良，或是由此引起的运转失常而可能会危及生命、身体或是财产，以及有可能给社会造成深刻影响的以下设备（不包括本产品目录或是交货规格说明书中另行注明可以使用设备）等时，请务必事先向敝公司咨询。

(1) 运输用设备（汽车驱动控制设备、火车控制设备、船舶控制设备等）
(2) 交通信号设备
(3) 防灾 / 保安设备
(4) 医疗设备（国际（GHTF）第三类）
(5) 高公共性信息通讯设备 / 信息处理设备（电话交换机、电话 / 无线 / 广播电视基站等）
(6) 其他与上述设备有同等品质与可靠性要求的设备

3. 禁止使用的设备

请勿将敝公司产品使用于对安全性和可靠性有着极高要求的以下设备。

(1) 航天设备（人工卫星、火箭等）
(2) 航空设备(注释1)
(3) 医疗设备（国际（GHTF）第四类）、植体（体内植入型）医疗设备(注释2)
(4) 发电控制设备（面向核能 / 水力 / 火力发电厂等的设备）
(5) 海底设备（海底中继设备、海中的作业设备等）
(6) 军事设备
(7) 其他与上述设备有同等品质与可靠性要求的设备

注释1：仅限于对航空设备的安全运行不产生直接干扰的设备［机内娱乐设备、机内照明设备、电动座椅、餐饮设备等］，在满足敝公司另行指定的相关条件时，亦可将敝公司产品用于以上用途。在贵公司考虑将敝公司的产品用于以上用途时，请务必事先向敝公司咨询相关的信息。

注释2：包括注入人体内的部分和与此相连接的体外部分。

4. 责任的限制

未经敝公司的事先书面同意，把本产品目录中所记载的产品使用于非敝公司预设用途的设备、前述需要向敝公司咨询的设备或敝公司禁止使用的设备，从而给客户或第三方造成损害的，敝公司不承担任何责任，敬请知悉。

安全设计

需将敝公司的产品使用于对安全性和可靠性要求较高的设备、电路上时，请进行充分的安全性评估和可靠性评估。另外，请通过设置保护电路、保护装置的系统，设置冗余电路不会被单一故障影响安全性的系统等失效导向安全（fail-safe）设计，确保充分的安全性。

有关知识产权

本产品目录中所记载的信息是用于说明相关产品的典型操作以及相关应用。此类信息的使用不代表对于敝公司以及第三方的知识产权以及其他权利的使用许可或是不侵权保证。

保证范围

敝公司产品的保证范围仅限于符合交货规格说明书中所记载的产品规格且已经交付的敝公司产品本身，由敝公司产品的故障或不良情况所诱发的损害，敝公司不承担任何责任，敬请知悉。但是，仅限于敝公司的产品作为通用性，标准性用途使用于本产品目录或是交货规格说明书中另行注明的设备，且以书面形式另行签署了交易基本合同书，品质保证协定书等时，敝公司将根据该合同等的条件提供保证。

正规销售渠道

本产品目录中所记载的内容适用于从敝公司营业所、销售子公司、销售代理店（即“正规销售渠道”）购买的敝公司产品，并不适用于从其他渠道购买的敝公司产品，敬请知悉。

出口时的注意事项

本产品目录中所记载的部分产品在出口时须事先确认《外汇和对外贸易法》以及美国在出口管理方面的相关法规，并办理相关手续。如有不明之处，请向敝公司咨询。

▶由于篇幅有限，本产品目录中只记载了有代表性的产品规格，若考虑使用敝公司产品时，请确认交货规格说明书中的详细规格。
另外，有关各产品的详细信息(特性图、可靠性信息、使用时的注意事项等)，请参阅敝公司网站(http://www.ty-top.com/)。

一般民生用 多层陶瓷电容器

回流焊

■型号标示法

M	S	A	S	U	3	1	L	B	B	5	1	0	6	K	T	N	A	0	1
①				②	③		④	⑤	⑥		⑦			⑧	⑨	⑩			

①系列

代码 (1) (2) (3) (4)	
MSAS	一般民生用 多层陶瓷电容器（高介电常数） 一般民生用 多层陶瓷电容器（温度补偿用） 一般民生用 中高耐压多层陶瓷电容器
MSAR	一般民生用 高频/低损耗中高耐压多层陶瓷电容器
MSAY	一般民生用 低失真设计/声音/良好偏置多层陶瓷电容器
MSRL	一般民生用 LW 反转/低 ESL 多层陶瓷电容器(LWDC™)

(1) 产品群

代码	
M	多层陶瓷电容器

(2) 范畴

代码	推荐设备	品质等级
S	一般民生用电子设备	3

(3) 类型

代码	
A	2 端接
R	LW 反转

(4) 特效 / 特性

代码	
S	标准/一般
R	高频/低损耗
Y	低失真设计/声音/良好偏置
L	低 ESL

②额定电压

代码	额定电压 [VDC]
P	2.5
A	4
J	6.3
L	10
E	16
T	25
G	35
U	50
H	100
Q	250
S	630
X	2000

③外型尺寸

代码	L×W [mm]	JIS(mm)	EIA(inch)
02	0.25× 0.125	0201	008004
04	0.4 × 0.2	0402	01005
06	0.6 × 0.3	0603	0201
1L	1.0 × 0.5	1005	0402
10	1.0 × 0.5	1005	0402
	0.52× 1.0 ※	0510	0204
16	1.6 × 0.8	1608	0603
	0.8 × 1.6 ※	0816	0306
21	2.0 × 1.25	2012	0805
	1.25× 2.0 ※	1220	0508
31	3.2 × 1.6	3216	1206
32	3.2 × 2.5	3225	1210
45	4.5 × 3.2	4532	1812

注： ※LW 反转型（MSRL）

④产品厚度

代码	产品厚度 [mm]
1	0.125
H	0.13 (1.5 max ※)
E	0.18 (1.1 max ※)
2	0.2
3	0.3
K	0.45
5	0.5
8	0.8
9	0.85
Q	1.15
G	1.25
L	1.6
N	1.9 (0.088 ※)
Y	2.0 max
M	2.5

注： ※LW 反转型（MSRL）

⑤产品尺寸公差

代码	外型尺寸记号	L [mm]	W [mm]	T [mm]	产品厚度代
A	06	0.6±0.05	0.3±0.05	0.3±0.05	3
	10	1.0±0.10	0.5±0.10	0.5±0.10	5
	16	1.6+0.15/−0.05	0.8+0.15/−0.05	0.8+0.15/−0.05	8
	21	2.0+0.15/−0.05	1.25+0.15/−0.05	1.25+0.15/−0.05	G
	31	3.2±0.20	1.6±0.20	1.6±0.20	L
	32	3.2±0.30	2.5±0.30	2.5±0.30	M
	45	4.5±0.40	3.2±0.30	2.0+0/−0.30	Y
B	06	0.6±0.09	0.3±0.09	0.3±0.09	3
	10	1.0+0.15/−0.05	0.5+0.15/−0.05	0.5+0.15/−0.05	5
	16	1.6+0.20/−0	0.8+0.20/−0	0.8+0.20/−0	8
	21	2.0+0.20/−0	1.25+0.20/−0	1.25+0.20/−0	G
	31	3.2±0.30	1.6±0.30	1.6±0.30	L
	32	3.2±0.30	2.5±0.20	1.9+0.1/−0.20	Y
C	10	1.0+0.20/−0	0.5+0.20/−0	0.5+0.20/−0	5
E	06	0.6+0.25/−0	0.3+0.25/−0	0.3+0.25/−0	3
	10	1.0+0.30/−0	0.5+0.30/−0	0.5+0.30/−0	5
H	31	3.2±0.15	1.6±0.15	0.85±0.10	9
				1.15±0.10	Q
J	16	1.6+0.20/−0	0.8+0.20/−0	0.45±0.05	K
	21	2.0+0.15/−0.05	1.25+0.15/−0.05	0.85±0.10	9
	32	3.2±0.30	2.5±0.20	0.85±0.10	9
				1.15±0.10	Q
L	21	2.0+0.20/−0	1.25+0.20/−0	0.85±0.10	9
	31	3.2±0.20	1.6±0.20	0.85±0.10	9
S	02	0.25±0.013	0.125±0.013	0.125±0.013	1
	04	0.4±0.02	0.2±0.02	0.2±0.02	2
	06	0.6±0.03	0.3±0.03	0.3±0.03	3
	10	1.0±0.05	0.5±0.05	0.5±0.05	5
		0.52±0.05 ※	1.0±0.05	0.3±0.05	3
	16	1.6±0.10	0.8±0.10	0.8±0.10	8
		0.8±0.10 ※	1.6±0.10	0.5±0.05	5
	21	2.0±0.10	1.25±0.10	0.85±0.10	9
				1.25±0.10	G
		1.25±0.15 ※	2.0±0.15	0.85±0.10	9
	31	3.2±0.15	1.6±0.15	1.6±0.20	L
	32	3.2±0.30	2.5±0.20	2.5±0.20	M
				1.9±0.20	N
	45	4.5±0.40	3.2±0.30	2.5±0.20	M
T	16	1.6±0.10	0.8±0.10	0.45±0.05	K
X	1L	1.0±0.05	0.5±0.05	0.13±0.02	H
				0.18±0.02	E
				0.2±0.02	2
Y	1L	1.0±0.05	0.5±0.05	0.3±0.03	3

注： ※LW 反转型（MSRL）

⑥温度特性

■高介电常数【SD：低失真设计/声音/良好偏置多层陶瓷电容器除外】

代码	适用标准		温度范围［℃］	基准温度［℃］	静电容量变化率	静电容量允许偏差	允许偏差代码
B5	JIS	B	−25～＋ 85	20	±10%	±10%	K
						±20%	M
	EIA	X5R	−55～＋ 85	25	±15%	±10%	K
						±20%	M
B7	EIA	X7R	−55～＋125	25	±15%	±10%	K
						±20%	M
C6	EIA	X6S	−55～＋105	25	±22%	±10%	K
						±20%	M
C7	EIA	X7S	−55～＋125	25	±22%	±10%	K
						±20%	M
LD(※)	EIA	X5R	−55～＋ 85	25	±15%	±10%	K
						±20%	M

注： ※LD：低失真设计/声音/良好偏置多层陶瓷电容器

■温度补偿用

代码	适用标准		温度范围［℃］	基准温度［℃］	静电容量变化率	静电容量允许偏差	允许偏差代码
CG	JIS	CG	−55～＋125	20	0±30ppm/℃	±0.05pF	A
						±0.1pF	B
						±0.25pF	C
	EIA	C0G		25		±0.5pF	D
						±2%	G
						±5%	J
CH	JIS	CH	−55～＋125	20	0±60ppm/℃	±0.05pF	A
						±0.1pF	B
						±0.25pF	C
	EIA	C0H		25		±0.5pF	D
						±2%	G
						±5%	J
CJ	JIS	CJ	−55～＋125	20	0±120ppm/℃	±0.05pF	A
						±0.1pF	B
	EIA	C0J		25		±0.25pF	C
CK	JIS	CK	−55～＋125	20	0±250ppm/℃	±0.05pF	A
						±0.1pF	B
	EIA	C0K		25		±0.25pF	C

⑥系列名称

・低失真设计/声音/良好偏置多层陶瓷电容器

代码	系列名称
SD	标准品

・中高耐压多层陶瓷电容器

代码	系列名称
SD	标准品

⑦静电容量

代码（例）	静电容量
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	0.01μF
104	0.1μF
105	1μF
106	10μF
107	100μF

注： R＝小数点

⑧静电容量允许偏差

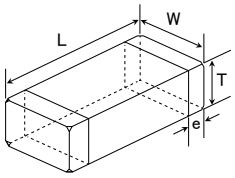
代码	静电容量允许偏差
A	±0.05pF
B	±0.1pF
C	±0.25pF
D	±0.5pF
G	±2%
J	±5%
K	±10%
M	±20%

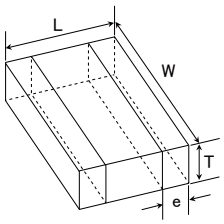
⑨包装

代码	包装规格
F	φ178mm 卷盘带装 （2mm 间隔）
T	φ178mm 卷盘带装 （4mm 间隔）
P	φ178mm 卷盘带装 （4mm 间隔，1000 个/卷盘）3225 规格（厚度代码 M）
R	φ178mm 压模带 1005 规格（2mm 间隔） 1608 规格（4mm 间隔）
W	φ178mm 压模带（1mm 间隔） 0201/0402 规格

⑩管理记号

■标准产品尺寸





※LW 反转型

Type	JIS (mm)	EIA (inch)	标准产品尺寸 [mm]				
			L	W	T	*1	e
MSAS□02	0201	008004	0.25±0.013	0.125±0.013	0.125±0.013	1	0.0675±0.0275
MSAR□02	0201	008004	0.25±0.013	0.125±0.013	0.125±0.013	1	0.0675±0.0275
MSAS□04	0402	01005	0.4±0.02	0.2±0.02	0.2±0.02	2	0.1±0.03
MSAR□04	0402	01005	0.4±0.02	0.2±0.02	0.2±0.02	2	0.1±0.03
MSAS□06	0603	0201	0.6±0.03	0.3±0.03	0.3±0.03	3	0.15±0.05
MSAS□1L	1005	0402	1.0±0.05	0.5±0.05	0.13±0.02	H	0.25±0.10
					0.18±0.02	E	
					0.2±0.02	2	
					0.3±0.03	3	
MSAS□10	1005	0402	1.0±0.05	0.5±0.05	0.5±0.05	5	0.25±0.10
MSAY□1L	1005	0402	1.0±0.05	0.5±0.05	0.3±0.03	3	0.25±0.10
MSAY□10	1005	0402	1.0±0.05	0.5±0.05	0.5±0.05	5	0.25±0.10
MSRL□10 ※	0510	0204	0.52±0.05	1.0±0.05	0.3±0.05	3	0.18±0.08
MSAS□16	1608	0603	1.6±0.10	0.8±0.10	0.45±0.05	K	0.35±0.25
					0.8±0.10	8	
MSAY□16	1608	0603	1.6±0.10	0.8±0.10	0.8±0.10	8	0.35±0.25
MSRL□16 ※	0816	0306	0.8±0.10	1.6±0.10	0.5±0.05	5	0.25±0.15
MSAS□21 MSAY□21	2012	0805	2.0±0.10	1.25±0.10	0.85±0.10	9	0.5±0.25
					1.25±0.10	G	
MSRL□21 ※	1220	0508	1.25±0.15	2.0±0.15	0.85±0.10	9	0.3±0.2
MSAS□31	3216	1206	3.2±0.15	1.6±0.15	0.85±0.10	9	0.5+0.35/−0.25
					1.15±0.10	Q	
					1.6±0.20	L	
MSAY□31	3216	1206	3.2±0.15	1.6±0.15	1.15±0.10	Q	0.5+0.35/−0.25
					1.6±0.20	L	
MSAS□32	3225	1210	3.2±0.30	2.5±0.20	0.85±0.10	9	0.6±0.3
					1.15±0.10	Q	
					1.9±0.20	N	
					1.9+0.1/−0.20	Y	
					2.5±0.20	M	
MSAY□32	3225	1210	3.2±0.30	2.5±0.20	1.9±0.20	N	0.6±0.3
					2.5±0.20	M	
MSAS□45	4532	1812	4.5±0.40	3.2±0.30	2.0+0/−0.30	Y	0.6±0.4
					2.5±0.20	M	0.9±0.6

注： ※LW 反转型（MSRL）、*1 产品厚度代码

■标准包装

外型			产品厚度		标准数量 [pcs]	
代码	JIS(mm)	EIA(inch)	[mm]	代码	纸带	压模带
02	0201	008004	0.125	1	—	50000
04	0402	01005	0.2	2	—	40000
06	0603	0201	0.3	3	15000	—
1L	1005	0402	0.13	H	—	20000
			0.18	E	—	15000
			0.2	2	20000	—
			0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204 ※	0.3	3		
16	1608	0603	0.45	K	4000	—
			0.8	8		
	0816 ※	0306 ※	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
	1220 ※	0508 ※	0.85	9	4000	—
31	3216	1206	0.85	9	4000	—
			1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	0.85	9	—	2000
			1.15	Q		
			1.9	N		
			2.0 max	Y		
			2.5	M	—	1000
45	4532	1812	2.0 max	Y	—	1000
			2.5	M	—	500

注： ※LW 反转型（MSRL）

■PART NUMBER

LW Reversal Decoupling Low ESL Capacitors (LWDC™) for General Electronic Equipment for Consumer

●0510TYPE

【Temperature Characteristic B5(BJ) : X5R(−55～+85℃)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLT103SB5104MFNA01	TWK105 BJ104MP-F	25		X5R	0.1 μ	±20	5	150	0.3±0.05	
MSRLE103SB5224MFNA01	EWK105 BJ224MP-F	16		X5R	0.22 μ	±20	10	150	0.3±0.05	
MSRLL103SB5474MFNA01	LWK105 BJ474MP-F	10		X5R	0.47 μ	±20	10	150	0.3±0.05	
MSRLJ103SB5104MFNA01	JWK105 BJ104MP-F	6.3		X5R*1	0.1 μ	±20	5	150	0.3±0.05	
MSRLJ103SB5474MFNA01	JWK105 BJ474MP-F			X5R*1	0.47 μ	±20	10	150	0.3±0.05	
MSRLJ103SB5105MFNA01	JWK105 BJ105MP-F			X5R	1 μ	±20	10	150	0.3±0.05	
MSRLJ103SB5225MFNA01	JWK105 BJ225MP-F			X5R	2.2 μ	±20	10	150	0.3±0.05	

【Temperature Characteristic C6 : X6S(−55～+105℃), C7 : X7S(−55～+125℃)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLE103SC6104MFNA01	EWK105 C6104MP-F	16		X6S	0.1 μ	±20	5	150	0.3±0.05	
MSRLL103SC7104MFNA01	LWK105 C7104MP-F	10		X7S	0.1 μ	±20	5	150	0.3±0.05	
MSRLL103SC6224MFNA01	LWK105 C6224MP-F			X6S	0.22 μ	±20	10	150	0.3±0.05	
MSRLJ103SC7104MFNA01	JWK105 C7104MP-F	6.3		X7S	0.1 μ	±20	5	150	0.3±0.05	
MSRLJ103SC7224MFNA01	JWK105 C7224MP-F			X7S	0.22 μ	±20	10	150	0.3±0.05	
MSRLJ103SC6474MFNA01	JWK105 C6474MP-F			X6S	0.47 μ	±20	10	150	0.3±0.05	
MSRLA103SC6224MFNA01	AWK105 C6224MP-F	4		X6S	0.22 μ	±20	10	150	0.3±0.05	
MSRLA103SC6474MFNA01	AWK105 C6474MP-F			X6S	0.47 μ	±20	10	150	0.3±0.05	
MSRLA103SC6105MFNA01	AWK105 C6105MP-F			X6S	1 μ	±20	10	150	0.3±0.05	
MSRLA103SC6225MFNA01	AWK105 C6225MP-F			X6S	2.2 μ	±20	10	150	0.3±0.05	

●0816TYPE

【Temperature Characteristic B5(BJ) : X5R(−55～+85℃)】 0.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLT165SB5104MTNA01	TWK107 BJ104MV-T	25		X5R*1	0.1 μ	±20	5	150	0.5±0.05	
MSRLE165SB5224MTNA01	EWK107 BJ224MV-T	16		X5R*1	0.22 μ	±20	5	150	0.5±0.05	
MSRLE165SB5474MTNA01	EWK107 BJ474MV-T			X5R*1	0.47 μ	±20	5	150	0.5±0.05	
MSRLL165SB5105MTNA01	LWK107 BJ105MV-T	10		X5R	1 μ	±20	10	150	0.5±0.05	
MSRLL165SB5225MTNA01	LWK107 BJ225MV-T			X5R	2.2 μ	±20	10	150	0.5±0.05	
MSRLJ165SB5105MTNA01	JWK107 BJ105MV-T	6.3		X5R*1	1 μ	±20	10	150	0.5±0.05	
MSRLJ165SB5225MTNA01	JWK107 BJ225MV-T			X5R	2.2 μ	±20	10	150	0.5±0.05	
MSRLJ165SB5475MTNA01	JWK107 BJ475MV-T			X5R	4.7 μ	±20	10	150	0.5±0.05	
MSRLA165SB5106MTNA01	AWK107 BJ106MV-T	4		X5R	10 μ	±20	10	150	0.5±0.05	

【Temperature Characteristic B7 : X7R(−55～+125℃), C6 : X6S(−55～+105℃), C7 : X7S(−55～+125℃)】 0.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLT165SB7104MTNA01	TWK107 B7104MV-T	25		X7R	0.1 μ	±20	5	150	0.5±0.05	
MSRLE165SB7224MTNA01	EWK107 B7224MV-T	16		X7R	0.22 μ	±20	5	150	0.5±0.05	
MSRLE165SB7474MTNA01	EWK107 B7474MV-T			X7R	0.47 μ	±20	5	150	0.5±0.05	
MSRLJ165SC7105MTNA01	JWK107 C7105MV-T	6.3		X7S	1 μ	±20	10	150	0.5±0.05	
MSRLA165SC7225MTNA01	AWK107 C7225MV-T	4		X7S	2.2 μ	±20	10	150	0.5±0.05	
MSRLA165SC6475MTNA01	AWK107 C6475MV-T			X6S	4.7 μ	±20	10	150	0.5±0.05	
MSRLP165SC6106MTNA01	PWK107 C6106MV-T	2.5		X6S	10 μ	±20	10	150	0.5±0.05	

●1220TYPE

【Temperature Characteristic B5(BJ) : X5R(−55～+85℃)】 0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLT219SB5475□TNA01	TWK212 BJ475□D-T	25		X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MSRLE219SB5106MTNA01	EWK212 BJ106MD-T	16		X5R	10 μ	±20	10	150	0.85±0.10	
MSRLL219SB5475□TNA01	LWK212 BJ475□D-T	10		X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MSRLL219SB5106MTNA01	LWK212 BJ106MD-T			X5R	10 μ	±20	10	150	0.85±0.10	
MSRLJ219SB5226MTNA01	JWK212 BJ226MD-T	6.3		X5R	22 μ	±20	10	150	0.85±0.10	

【Temperature Characteristic B7 : X7R(−55～+125℃), C6 : X6S(−55～+105℃)】 0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
MSRLT219SB7225□TNA01	TWK212 B7225□D-T	25		X7R	2.2 μ	±10, ±20	5	150	0.85±0.10	
MSRLE219SC6475□TNA01	EWK212 C6475□D-T	16		X6S	4.7 μ	±10, ±20	10	150	0.85±0.10	
MSRLL219SC6106MTNA01	LWK212 C6106MD-T	10		X6S	10 μ	±20	10	150	0.85±0.10	
MSRLA219SC6226MTNA01	AWK212 C6226MD-T	4		X6S	22 μ	±20	10	150	0.85±0.10	

■PACKAGING

①Minimum Quantity

●Taped package

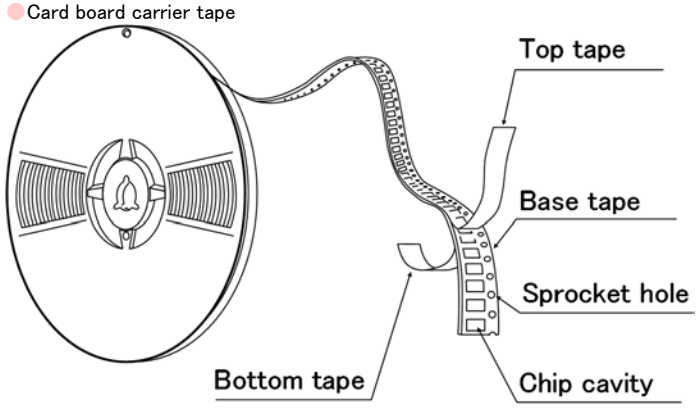
Type			Thickness		Standard Quantity[pcs]	
Code	JIS(mm)	EIA(inch)	[mm]	Code	Paper tape	Embossed tape
02	0201	008004	0.125	1	—	50000
04	0402	01005	0.2	2	—	40000
06	0603	0201	0.3	3	15000	—
1L	1005	0402	0.13	H	—	20000
			0.18	E	—	15000
			0.2	2	20000	—
			0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204	0.3	3	10000	—
16	1608	0603	0.45	K	4000	—
			0.7	7		
			0.8	8		
			0.8	8	3000 (Soft Termination)	3000 (Soft Termination)
	0816 ※	0306	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
			1.25	G	—	2000 (Soft Termination)
	1220 ※	0508	0.85	9	4000	—
31	3216	1206	0.85	9	4000	—
			1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	0.85	9	—	2000
			1.15	Q		
			1.9	N		
			2.0 max	Y		
			2.5	M	—	500(T), 1000(P)
45	4532	1812	2.0 max	Y	—	1000
			2.5	M	—	500

注:※LW Reverse type (MSRL, MCRL, MBRL, MLRL, MMRL)

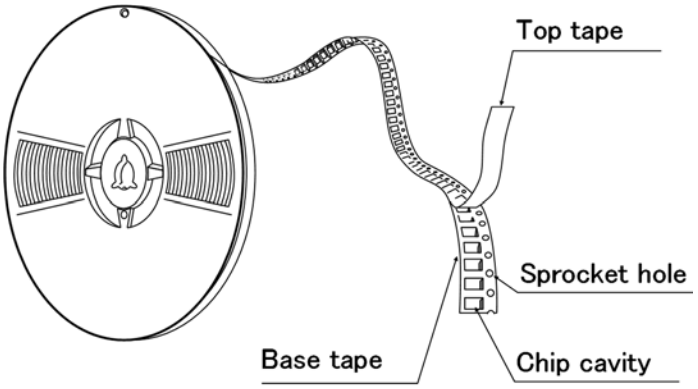
②Taping material

※No bottom tape for pressed carrier tape

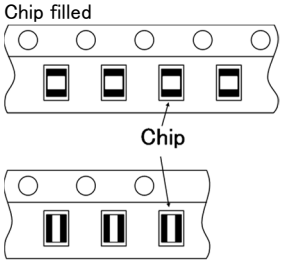
Card board carrier tape



Embossed tape



Chip filled



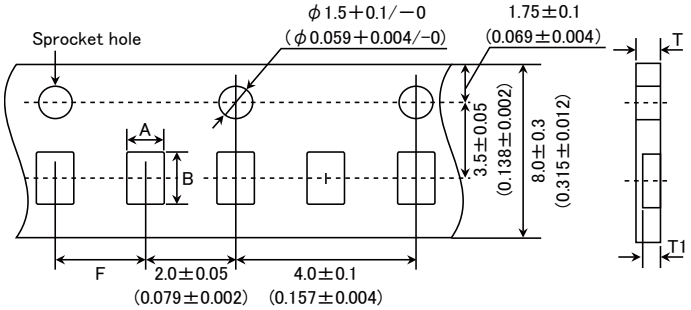
※ LW Reverse type.

③Representative taping dimensions

Paper Tape(8mm wide)

●Pressed carrier tape(2mm pitch)

Unit:mm(inch)



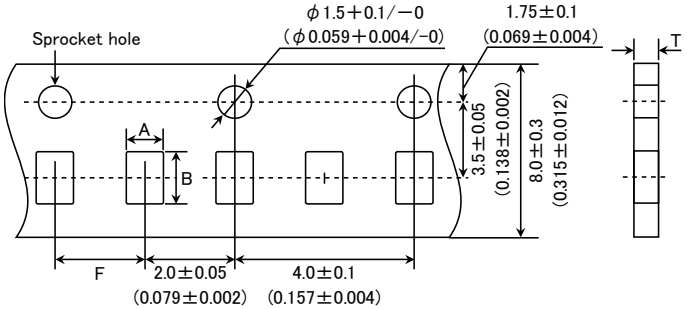
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	T	T1
0603 (0201)	0.37	0.67	2.0±0.05	0.45max.	0.42max.
0510 (0204) ※	0.65	1.15			
1005 (0402) (*1 2)				0.4max.	0.3max.
1005 (0402) (*1 3)				0.45max.	0.42max.

Note *1 Thickness, 2:0.2mm , 3:0.3mm. ※ LW Reverse type.

Unit:mm

●Punched carrier tape (2mm pitch)

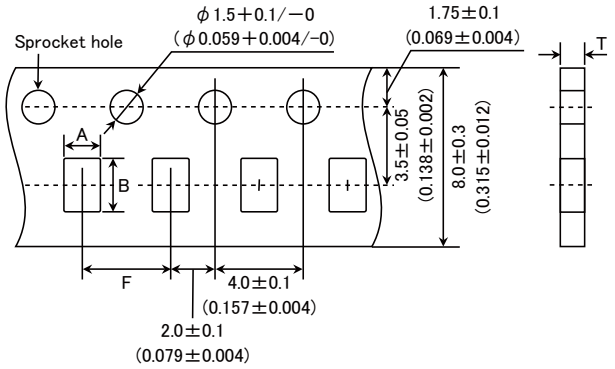
Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B	F	T
1005 (0402)	0.65	1.15	2.0±0.05	0.8max.

Unit:mm

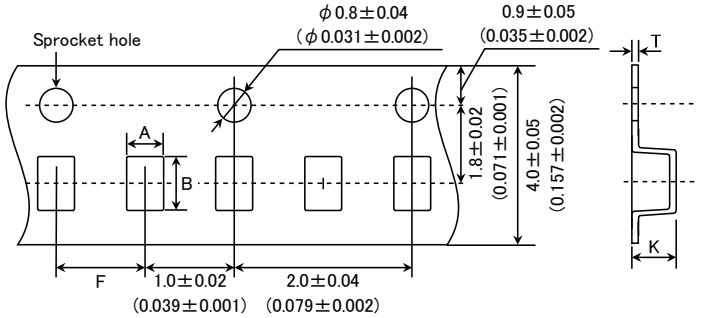
●Punched carrier tape (4mm pitch)　　Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B	F	T
1608 (0603) 0816 (0306) ※	1.0	1.8	4.0±0.1	1.1max.
2012 (0805) 1220 (0508) ※	1.65	2.4		1.1max.
3216 (1206)	2.0	3.6		

Note:Taping size might be different depending on the size of the product. ※ LW Reverse type.　　Unit:mm

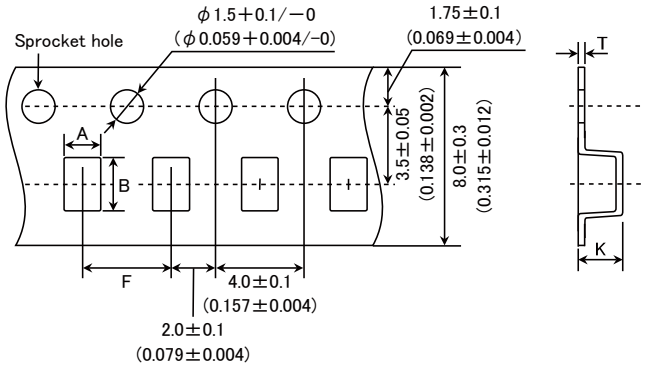
●Embossed tape(4mm wide)　　Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
0201 (008004)	0.135	0.27	1.0±0.02	0.5max.	0.25max.
0402 (01005)	0.23	0.43			

Unit:mm

●Embossed tape(8mm wide)　　Unit:mm(inch)

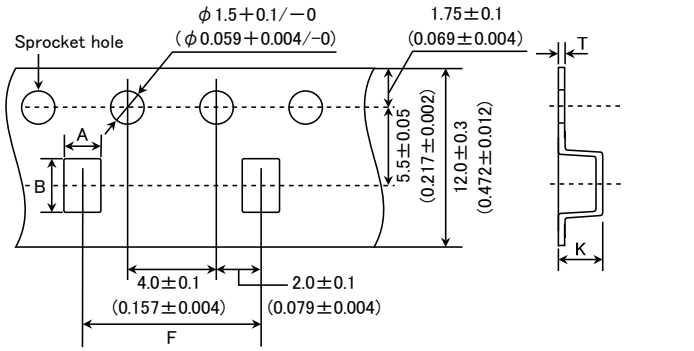


Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
1005 (0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
0816 (0306) ※	1.0	1.8	4.0±0.1	1.3max.	0.25±0.1
2012 (0805)	1.65	2.4		3.4max.	0.6max.
3216 (1206)	2.0	3.6			
3225 (1210)	2.8	3.6			

Note: ※ LW Reverse type.　　Unit:mm

Embossed tape (12mm wide)

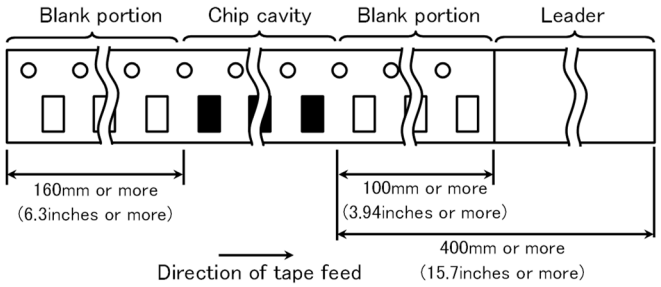
Unit : mm (inch)



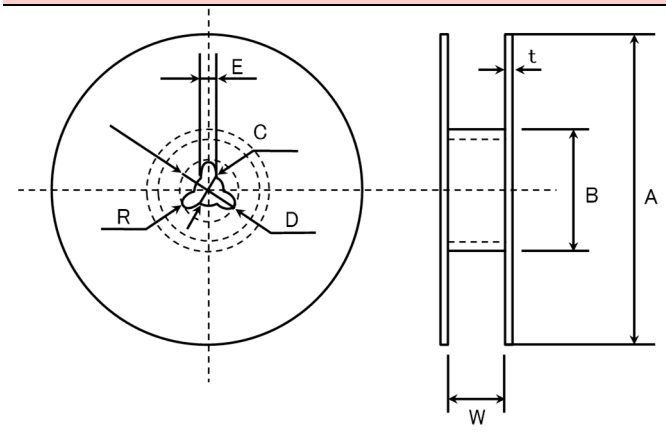
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
3225 (1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
4532 (1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit : mm

④Trailer and Leader



⑤Reel size



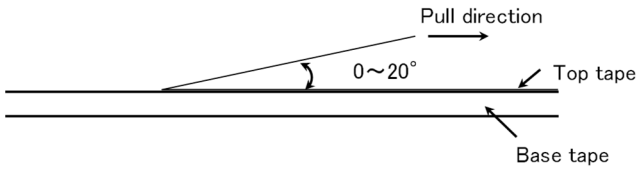
A	B	C	D	E	R
φ178±2.0	φ50min.	φ13.0±0.2	φ21.0±0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit : mm

⑥Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



Multilayer Ceramic Capacitors for General Electronic Equipment for Consumer
Multilayer Ceramic Capacitors
for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

■RELIABILITY DATA

1.Operating Temperature Range

Specified Value	Temperature Compensating(Class1)	Standard / High Frequency Type	−55 to +125℃
	High Permittivity (Class2)		

	Specification	Temperature Range
B5	B	−25 to +85℃
	X5R	−55 to +85℃
B7	X7R	−55 to +125℃
C6	X6S	−55 to +105℃
C7	X7S	−55 to +125℃

2. Storage Conditions

Specified Value	Temperature Compensating(Class1)	Standard / High Frequency Type	−55 to +125℃
	High Permittivity (Class2)		

	Specification	Temperature Range
B5	B	−25 to +85℃
	X5R	−55 to +85℃
B7	X7R	−55 to +125℃
C6	X6S	−55 to +105℃
C7	X7S	−55 to +125℃

3. Rated Voltage

Specified Value	Temperature Compensating(Class1)	Standard	50VDC, 25VDC, 16VDC
		High Frequency Type	25VDC, 16VDC
	High Permittivity (Class2)		50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC

4. Withstanding Voltage (Between terminals)

Specified Value	Temperature Compensating(Class1)	Standard / High Frequency Type	No breakdown or damage
	High Permittivity (Class2)		

Test Methods and Remarks		
	Class 1	Class 2
Applied voltage	Rated voltage × 3	Rated voltage × 2.5
Duration	1 to 5 sec.	
Charge/discharge current	50mA max.	

5. Insulation Resistance

Specified Value	Temperature Compensating(Class1)	Standard / High Frequency Type	10000 MΩ min.
	High Permittivity (Class2) Note 1		C≦0.047μF : 10000 MΩ min. C＞0.047μF : 500MΩ・μF (C:Nominal capacitance)
Test Methods and Remarks	Applied voltage : Rated voltage Duration : 60±5 sec. Charge/discharge current : 50mA max.		

6. Capacitance (Tolerance)

Specified Value

Temperature Compensating(Class1)	Standard	0.2pF≦C≦5pF : ±0.25pF 5pF≦C≦10pF : ±0.5pF C＞10pF : ±5%
	High Frequency Type	Refer to detailed specification
High Permittivity (Class2)		±10% or ±20%

Test Methods and Remarks

	Class 1		Class 2	
	Standard	High Frequency Type	C≦10μF	C＞10μF
Preconditioning	None		Thermal treatment (at 150℃ for 1hr) Note 2	
Measuring frequency	1MHz±10%	1GHz	1kHz±10%	120±10Hz
Measuring voltage Note 1	0.5 to 5Vrms		1±0.2Vrms	0.5±0.1Vrms
Bias application	None			

7. Q or Dissipation Factor

Specified Value

Temperature Compensating(Class1)	Standard	C＜30pF : Q≧400+20C C≧30pF : Q≧1000 (C:Nominal capacitance)
	High Frequency Type	Refer to detailed specification
High Permittivity (Class2) Note 1		2.5% max.

Test Methods and Remarks

	Class 1		Class 2	
	Standard	High Frequency Type	C≦10μF	C＞10μF
Preconditioning	None		Thermal treatment (at 150℃ for 1hr) Note 2	
Measuring frequency	1MHz±10%	1GHz	1kHz±10%	120±10Hz
Measuring voltage Note 1	0.5 to 5Vrms		1±0.2Vrms	0.5±0.1Vrms
Bias application	None			

8. Temperature Characteristic (Without voltage application)

Specified Value

Temperature Compensating(Class1) — Standard

Temperature Characteristic [ppm/℃]		Tolerance [ppm/℃]
C□ : 0	CG(C0G) CH(C0H) CJ(C0J) CK(C0K)	G:±30 H:±60 J:±120 H:±250

Temperature Compensating(Class1) — High Frequency Type

Temperature Characteristic [ppm/℃]		Tolerance [ppm/℃]
C□ : 0	CG(C0G) CH(C0H)	G:±30 H:±60

High Permittivity (Class2)

	Specification	Capacitance change	Reference temperature	Temperature Range
B5	B	±10%	20℃	−25 to +85℃
	X5R	±15%	25℃	−55 to +85℃
B7	X7R	±15%	25℃	−55 to +125℃
C6	XS	±22%	25℃	−55 to +105℃
C7	X7S	±22%	25℃	−55 to +125℃

Test Methods and Remarks

Class 1

Capacitance at 20℃ and 85℃ shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T}\times 10^{6}(\mathrm{ppm/℃}) \qquad \Delta T=65$$

Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

Step	B	X5R、X7R、X6S、X7S
1	Minimum operating temperature	
2	20℃	25℃
3	Maximum operating temperature	

$$\frac{(C-C_2)}{C_2}\times 100(\%)$$

C : Capacitance in Step 1 or Step 3

C_2 : Capacitance in Step 2

※Measuring frequency and voltage: Refer to detailed specification

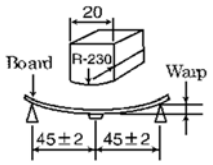
9. Deflection

Specified Value	Temperature Compensating(Class1)	Standard	Appearance : No abnormality Capacitance change : Within ±5% or ±0.5 pF, whichever is larger.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within±0.5 pF
	High Permittivity (Class2)		Appearance : No abnormality Capacitance change : Within ±12.5%

Test Methods and Remarks

	Multilayer Ceramic Capacitors	
	0201, 0402, 0603, ※1005 Type	The other types
Board	Glass epoxy-resin substrate	
Thickness	0.8mm	1.6mm
Warp	1mm	
Duration	10 sec.	

※1005 Type thickness, 2: 0.2mm , 3: 0.3mm.



(Unit: mm)

Capacitance measurement shall be conducted with the board bent

10. Adhesive Strength of Terminal Electrodes

Specified Value	Temperature Compensating(Class1)	Standard	No terminal separation or its indication.
		High Frequency Type	
	High Permittivity (Class2)		

Test Methods and Remarks

	0201Type	0402、0603Type	1005Type or more
Applied force	1N	2N	5N
Duration	10±1 sec		30±5 sec

11. Vibration

Specified Value	Temperature Compensating(Class1)	Standard	Initial performance shall be satisfied.
		High Frequency Type	
	High Permittivity (Class2)		

Test Methods and Remarks

Preconditioning : Thermal treatment(at 150℃ for 1hr) Note2 (Only High permittivity)
Frequency range : 10 to 55 Hz
Overall amplitude : 1.5 mm
Sweeping method : 10 to 55 to 10 Hz for 1 min
Two hours each in X, Y, Z directions: 6 hrs in total

12. Solderability

Specified Value	Temperature Compensating(Class1)	Standard	At least 95% of terminal electrode is covered by new solder.
		High Frequency Type	
	High Permittivity (Class2)		

Test Methods and Remarks

	Eutectic solder	Lead-free solder
Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu
Solder temperature	230±5℃	245±3℃
Duration	4±1 sec.	

13. Resistance to Soldering

Specified Value

Temperature Compensating(Class1)	Standard	Appearance : No abnormality Capacitance change : Within ±2.5% or ±0.25pF, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
	High Frequency Type	Appearance : No abnormality Capacitance change : Within ±2.5% or ±0.25pF, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within ±7.5% Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals): No abnormality

Test Methods and Remarks

	Class 1	
	0201, 0402, 0603 Type	1005 Type
Preconditioning	None	
Preheating	150℃, 1 to 2 min.	80 to 100℃, 2 to 5 min. 150 to 200℃, 2 to 5 min.
Solder temp.	270±5℃	
Duration	3±0.5 sec.	
Recovery	24±2 hrs (Standard condition) Note 5	

	Class 2		
	0201, 0402、0603 Type	1005, 1608, 2012 Type	3216, 3225, 4532 Type
Preconditioning	Thermal treatment (at 150℃ for 1 hr) Note 2		
Preheating	150℃, 1 to 2 min.	80 to 100℃, 2 to 5 min. 150 to 200℃, 2 to 5 min.	80 to 100℃, 5 to 10 min. 150 to 200℃, 5 to 10 min.
Solder temp.	270±5℃		
Duration	3±0.5 sec.		
Recovery	24±2 hrs (Standard condition) Note 5		

14. Temperature Cycle (Thermal Shock)

Specified Value

Temperature Compensating(Class1)	Standard	Appearance : No abnormality Capacitance change : Within ±2.5% or ±0.25pF, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
	High Frequency Type	Appearance : No abnormality Capacitance change : Within ±2.5% or ±0.25pF, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within ±7.5% Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality

Test Methods and Remarks

	Class 1	Class 2
Preconditioning	None	Thermal treatment (at 150℃ for 1 hr) Note 2
1 cycle		
Number of cycles	5 times	
Recovery	24±2 hrs (Standard condition) Note 5	

Step	Temperature(℃)	Time(min.)
1	Minimum operating temperature	30±3
2	Normal temperature	2 to 3
3	Maximum operating temperature	30±3
4	Normal temperature	2 to 3

15. Humidity (Steady State)			
Specified Value	Temperature Compensating(Class1)	Standard	Appearance : No abnormality Capacitance change : Within ±5% or ±0.5pF, whichever is larger. Q : C＜10pF : Q≧200＋10C 10≦C＜30pF : Q≧275＋2.5C C≧30pF:Q≧350(C:Nominal capacitance) Insulation resistance : 1000 MΩ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within ±5% or ±0.5pF, whichever is larger. Insulation resistance : 1000 MΩ min.
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within ±12.5% Dissipation factor : 5.0% max. Insulation resistance : 50 MΩ μF or 1000 MΩ whichever is smaller.
Test Methods and Remarks	Preconditioning : Thermal treatment(at 150℃ for 1hr) Note2 (Only High permittivity) Temperature : 40±2℃ Humidity : 90 to 95%RH Duration : 500 ＋24/－0 hrs Recovery : 24±2hrs under the standard condition Note 1,5		

16. Humidity Loading			
Specified Value	Temperature Compensating(Class1)	Standard	Appearance : No abnormality Capacitance change : Within ±7.5% or ±0.75pF, whichever is larger. Q : C＜30pF:Q≧100＋10C/3 C≧30pF:Q≧200 (C:Nominal capacitance) Insulation resistance : 500 MΩ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : C≦2pF:Within ±0.4 pF C＞2pF:Within ±0.75 pF C＞10pF: Within±0.75% (C:Nominal capacitance) Insulation resistance : 500 MΩ min.
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within ±12.5% Dissipation factor : 5.0% max. Insulation resistance : 25 MΩ μF or 500 MΩ, whichever is smaller.
Test Methods and Remarks	Preconditioning : Voltage treatment(Rated voltage are applied for 1 hour at 40℃) Note 1,3 (Only High permittivity) Temperature : 40±2℃ Humidity : 90 to 95%RH Duration : 500 ＋24/－0 hrs Applied voltage : Rated voltage Charge/discharge current : 50mA max. Recovery : 24±2hrs under the standard condition Note 1,5		

17. High Temperature Loading				
Specified Value	Temperature Compensating(Class1)	Standard	Appearance Capacitance change Q Insulation resistance	: No abnormality : Within ±3% or ±0.3pF, whichever is larger. : C＜10pF: Q≧200＋10C 10≦C＜30pF:Q≧275＋2.5C C≧30pF: Q≧350(C:Nominal capacitance) : 1000 MΩ min.
		High Frequency Type	Appearance Capacitance change Insulation resistance	: No abnormality : Within ±3% or ±0.3pF, whichever is larger. : 1000 MΩ min.
	High Permittivity (Class2) Note 1		Appearance Capacitance change Dissipation factor Insulation resistance	: No abnormality : Within ±12.5% : 5.0% max. : 50 MΩ μF or 1000 MΩ, whichever is smaller.
Test Methods and Remarks	Preconditioning Temperature Duration Applied voltage Charge/discharge current Recovery	: Voltage treatment(Twice the rated voltage shall be applied for 1 hour at 85℃, 105℃ or 125℃) Note 1,3,4 (Only High permittivity) : Maximum operating temperature : 1000 ＋24/－0 hrs : Rated voltage×2 Note 4 : 50mA max. : 24±2hrs under the standard condition Note 1,5		

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at 150＋0/－10℃ for an hour and kept at room temperature for 24±2hours.

Note 3 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.

Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.

Note 5 Standard condition: Temperature: 5 to 35℃, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.
Temperature: 20±2℃, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

■PRECAUTIONS

1. Circuit Design

Precautions

◆Verification of operating environment, electrical rating and performance

1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.
   Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

◆Operating Voltage (Verification of Rated voltage)

1. The operating voltage for capacitors must always be their rated voltage or less.
   If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
   For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

◆Pattern configurations (Design of Land-patterns)

1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
   (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
   (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.

◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

Technical considerations

◆Pattern configurations (Design of Land-patterns)

The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

(1) Recommended land dimensions for typical chip capacitors

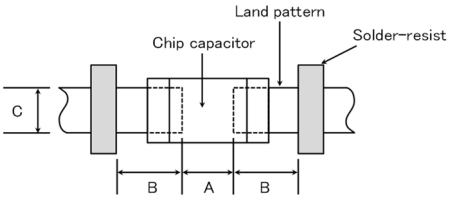
●Multilayer Ceramic Capacitors : Recommended land dimensions

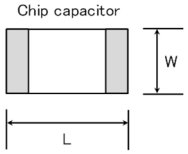
(unit: mm)

Wave-soldering

Type		1608	2012	3216	3225
Size	L	1.6	2.0	3.2	3.2
	W	0.8	1.25	1.6	2.5
A		0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5
B		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7
C		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5

Land patterns for PCBs





Reflow-soldering

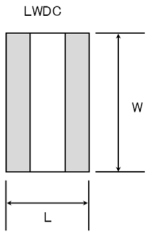
Type		0201	0402	0603	1005	1608	2012	3216	3225	4532
Size	L	0.25	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
	W	0.125	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
A		0.095～0.135	0.15～0.25	0.20～0.30	0.45～0.55	0.6～0.8	0.8～1.2	1.8～2.5	1.8～2.5	2.5～3.5
B		0.085～0.125	0.10～0.20	0.20～0.30	0.40～0.50	0.6～0.8	0.8～1.2	1.0～1.5	1.0～1.5	1.5～1.8
C		0.110～0.150	0.15～0.30	0.25～0.40	0.45～0.55	0.6～0.8	0.9～1.6	1.2～2.0	1.8～3.2	2.3～3.5

Note : Recommended land size might be different according to the allowance of the size of the product.

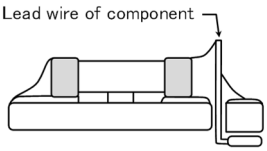
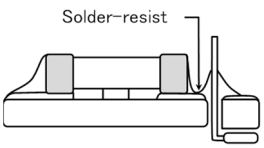
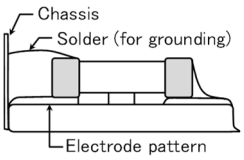
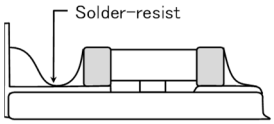
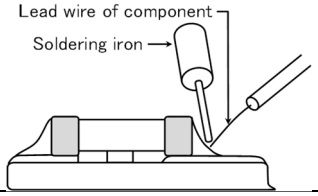
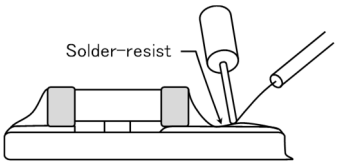
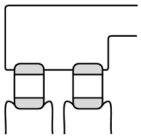
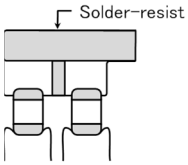
●LWDC: Recommended land dimensions for reflow-soldering

(unit: mm)

Type		0510	0816	1220
Size	L	0.52	0.8	1.25
	W	1.0	1.6	2.0
A		0.18～0.22	0.25～0.3	0.5～0.7
B		0.2～0.25	0.3～0.4	0.4～0.5
C		0.9～1.1	1.5～1.7	1.9～2.1

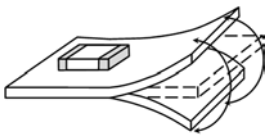
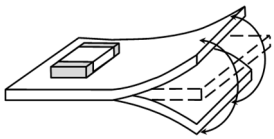


(2) Examples of good and bad solder application

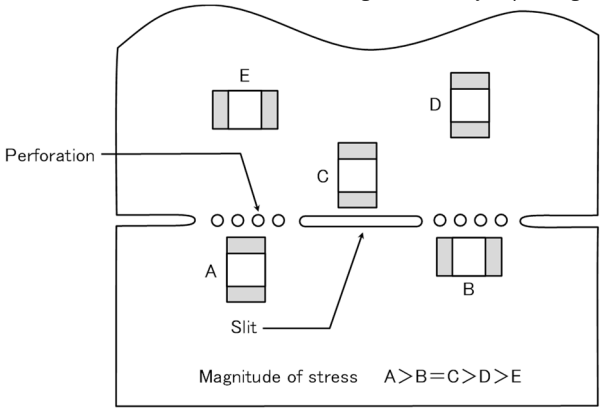
Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

◆Pattern configurations (Capacitor layout on PCBs)

1-1. The following is examples of good and bad capacitor layouts ; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		 Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

Precautions

◆Adjustment of mounting machine

1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
2. Maintenance and inspection of mounting machines shall be conducted periodically.

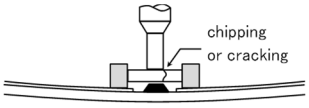
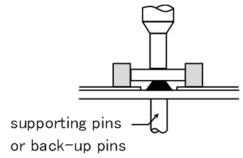
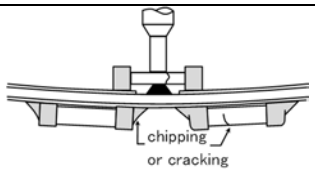
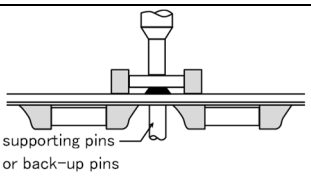
◆Selection of Adhesives

1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked : size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

Technical considerations

◆Adjustment of mounting machine

1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
   (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
   (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
   (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

Item	Improper method	Proper method
Single-sided mounting		
Double-sided mounting		

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.
   To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

◆Selection of Adhesives

Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

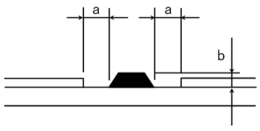
(1) Required adhesive characteristics
   a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
   b. The adhesive shall have sufficient strength at high temperatures.
   c. The adhesive shall have good coating and thickness consistency.
   d. The adhesive shall be used during its prescribed shelf life.
   e. The adhesive shall harden rapidly.
   f. The adhesive shall have corrosion resistance.
   g. The adhesive shall have excellent insulation characteristics.
   h. The adhesive shall have no emission of toxic gasses and no effect on the human body.

(2) The recommended amount of adhesives is as follows;

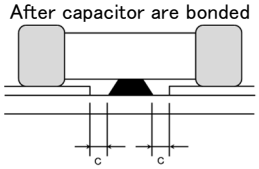
[Recommended condition]

Figure	2012/3216 case sizes as examples
a	0.3mm min
b	100 to 120 μm
c	Adhesives shall not contact land

Amount adhesive



After capacitor are bonded



4. Soldering

Precautions

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

(1) Flux used shall be less than or equal to 0.1 wt%(in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
(2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
(3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.
Sn-Zn solder paste can adversely affect MLCC reliability.
Please contact us prior to usage of Sn-Zn solder.

Technical considerations

◆Selection of Flux

1-1. When too much halogenated substance(Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods

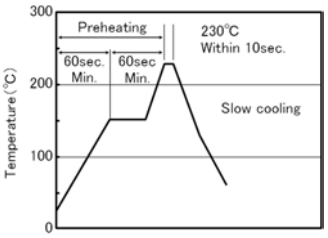
and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

◆Soldering

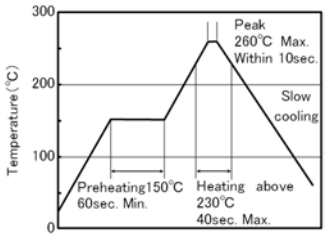
- Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock.
- Preheating : Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130℃.
- Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than 100℃.

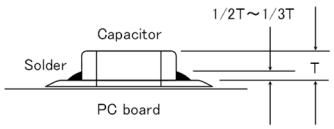
[Reflow soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】





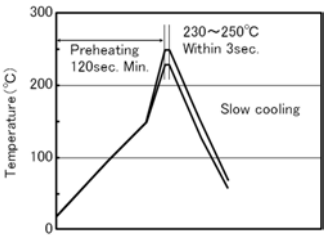
Caution

①The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.

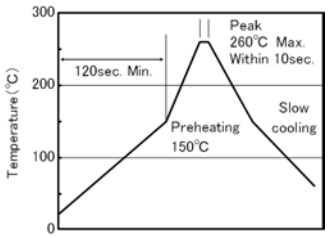
②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible. soldering for 2 times.

[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

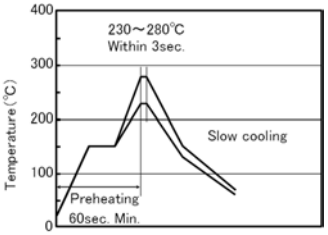


Caution

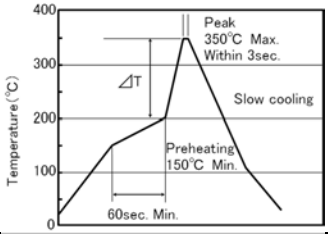
①Wave soldering must not be applied to capacitors designated as for reflow soldering only. soldering for 1 times.

[Hand soldering]

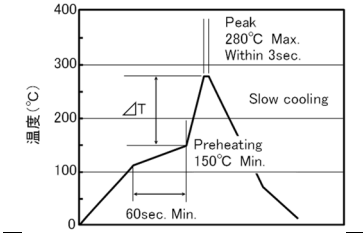
【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



	⊿T
3216type or less	⊿T≦150℃



	⊿T
3225type or more	⊿T≦130℃

Caution

①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.

②The soldering iron shall not directly touch capacitors. soldering for 1 times.

5. Cleaning	
Precautions	◆Cleaning conditions 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.
Technical considerations	1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions(insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked; Ultrasonic output : 20 W/ℓ or les Ultrasonic frequency : 40 kHz or less Ultrasonic washing period : 5 min. or less

6. Resin coating and mold	
Precautions	1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance. 2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors. The use of such resins, molding materials etc. is not recommended.

7. Handling	
Precautions	◆Splitting of PCB 1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board. 2. Board separation shall not be done manually, but by using the appropriate devices. ◆Mechanical considerations Be careful not to subject capacitors to excessive mechanical shocks. (1)If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used. (2)Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. ・Recommended conditions Ambient temperature : Below 30℃ Humidity : Below 70% RH The ambient temperature must be kept below 40℃. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery. ・Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air. 2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150℃ for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

※RCR-2335B(Safety Application Guide for fixed ceramic capacitors for use in electronic equipment)is published by JEITA.
Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.